

$R_{DS(ON)}$  (at  $V_{GS}=4.5V$ ) 1.4m  
100% EAS Tested  
100% VDS Tested

### General Description

Split gate trench MOSFET technology  
Excellent package for heat dissipation  
High density cell design for low  $R_{DS(ON)}$   
Epoxy Meets UL 94 V-0 Flammability Rating  
Halogen Free  
Moisture Sensitivity Level 1

### Applications

Power switching application  
Uninterruptible power supply  
DC-DCDN © 5 Æ

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	$T_A=25$	$I_D$	42	A
	$T_A=100$		29	
	$T_C=25$		300	
	$T_C=100$		212	
Pulsed Drain Current <sup>A</sup>		$I_{DM}$	1200	A
Avalanche energy <sup>B</sup>		EAS	1250	mJ
Total Power Dissipation <sup>C</sup>	$T_A=25$	$P_D$	3	W
	$T_A=100$		1.5	
	$T_C=25$		136	
	$T_C=100$		68	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 +175	

### Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient <sup>D</sup>	Steady-State	$R_{JA}$	40	50	/W
Thermal Resistance Junction-to-Case	Steady-State	$R_{JC}$	0.9	1.1	

### Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJG300G04AR	F1	G300G04AR	5000	10000	100000	13" reel



# YJG300G04AR

## Electrical Characteristics (T<sub>J</sub>=25 unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =1mA	40	-	-	V
		V <sub>GS</sub> = 0V, I <sub>D</sub> =10mA	40	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1	μA
		V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, T <sub>J</sub> =100	-	-	100	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	1	1.5	2.5	V
Static Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =50A	-	0.65	0.9	m
		V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	0.65	0.9	
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	1	1.4	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =50A, V <sub>GS</sub> =0V	-	-	1.2	V
Gate resistance	R <sub>G</sub>	f=1MHz	-	2	-	
Maximum Body-Diode Continuous Current	I <sub>S</sub>		-	-	300	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1MHz	-	6125	-	pF
Output Capacitance	C <sub>oss</sub>		-	3250	-	
Reverse Transfer Capacitance	C <sub>riss</sub>		-	150	-	
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, I <sub>D</sub> =50A	-	101	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	21	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	21	-	
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =50A, di/dt=100A/us	-	94	-	nC
Reverse Recovery Time	t <sub>rr</sub>		-	69	-	ns
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =10V, V <sub>DD</sub> =20V, I <sub>D</sub> =50A R <sub>GEN</sub> =3	-	16	-	ns
Turn-on Rise Time	t <sub>r</sub>		-	44	-	
Turn-off Delay Time	t <sub>D(off)</sub>		-	71	-	
Turn-off fall Time	t <sub>f</sub>		-	45	-	

A. Repetitive rating; pulse width limited by max. junction temperature.

B. T<sub>J</sub>=25 , V<sub>G</sub>=10V, R<sub>G</sub>=25 , L=4mH, I<sub>AS</sub>=25A.

C. P<sub>d</sub> is based on max. junction temperature, using junction-case thermal resistance.

D. The value of R<sub>JA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in the still air environment with T<sub>A</sub>=25 . The maximum allowed junction temperature of 175 . The value in any given application depends on the user's specific board design.





# YJG300G04AR

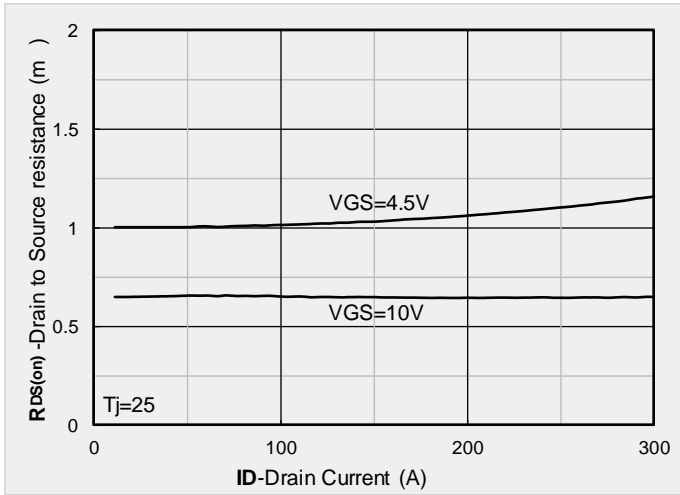


Figure 7. RDS(on) VS Drain Current

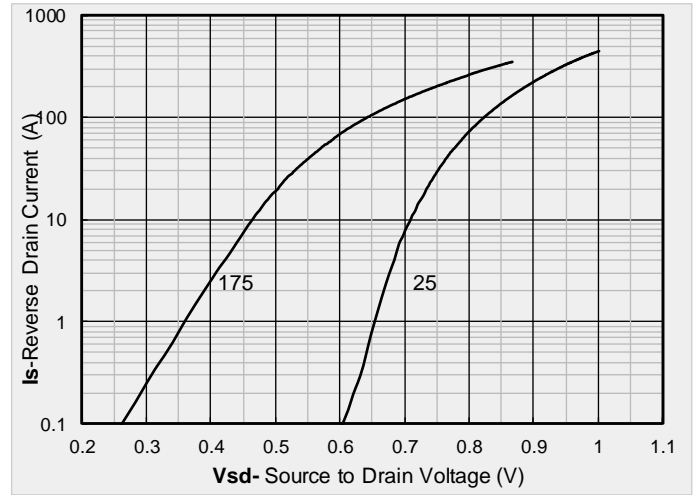
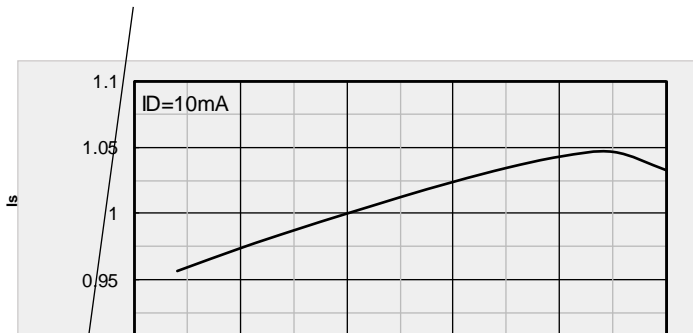


Figure 8. Forward characteristics of reverse diode



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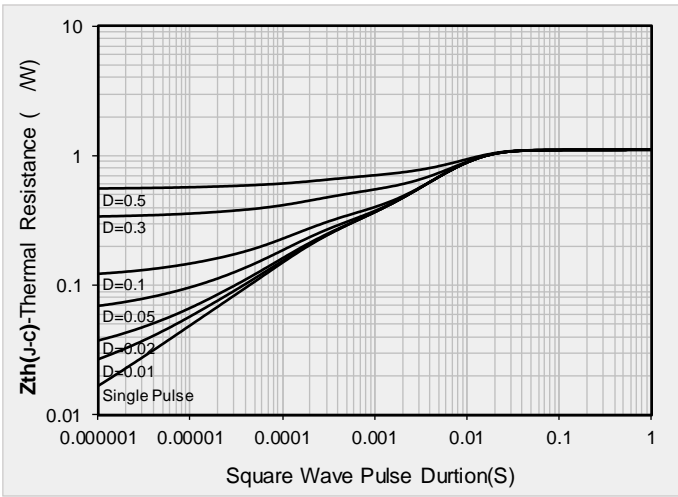


Figure 13. Maximum Transient Thermal Impedance

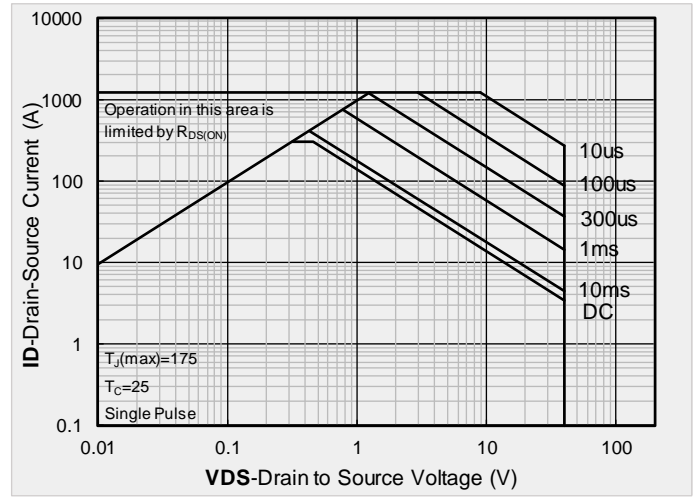
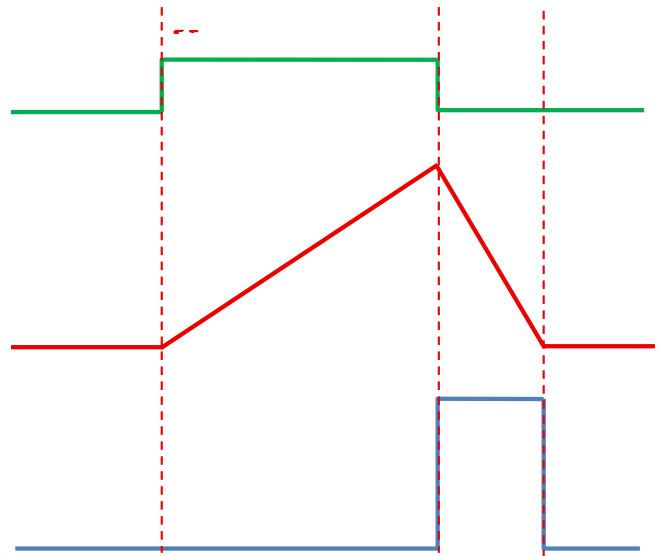
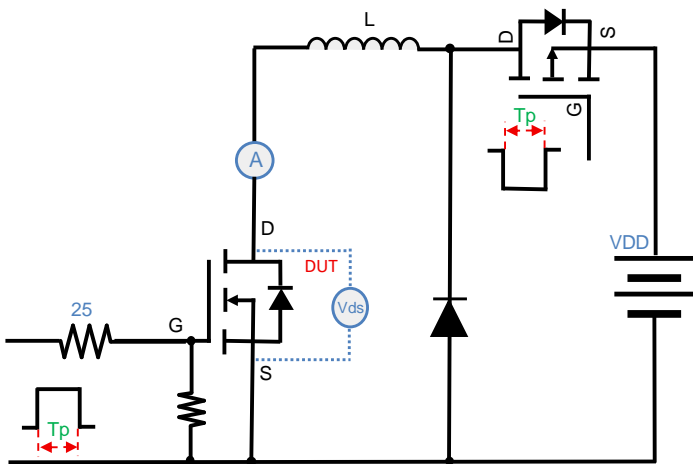


Figure 14. Safe Operation Area

## Test Circuits & Waveforms



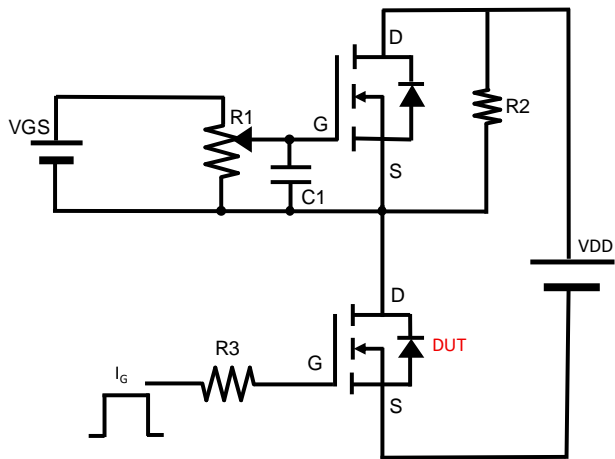


Figure B. Gate Charge Test Circuit & Waveform

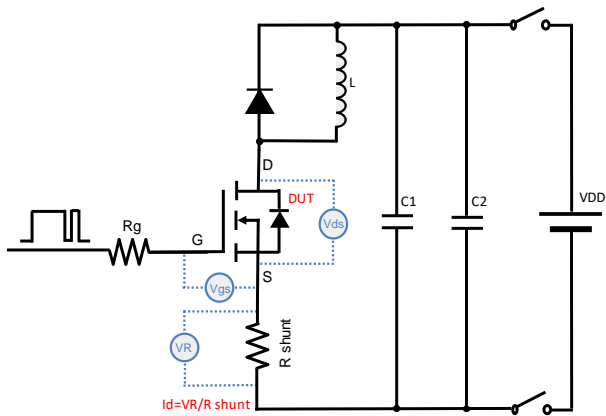


Figure C. Resistive Switching Test Circuit & Waveform

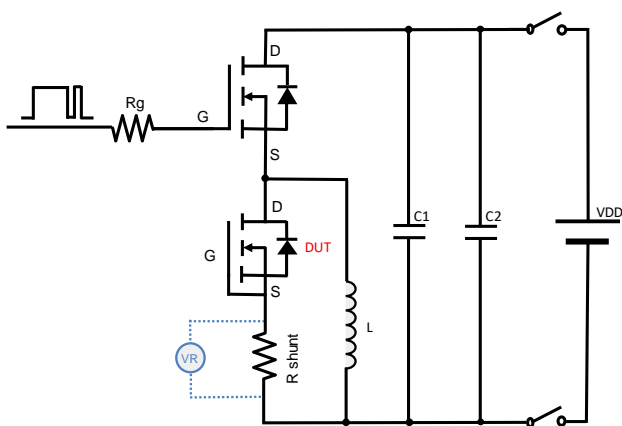
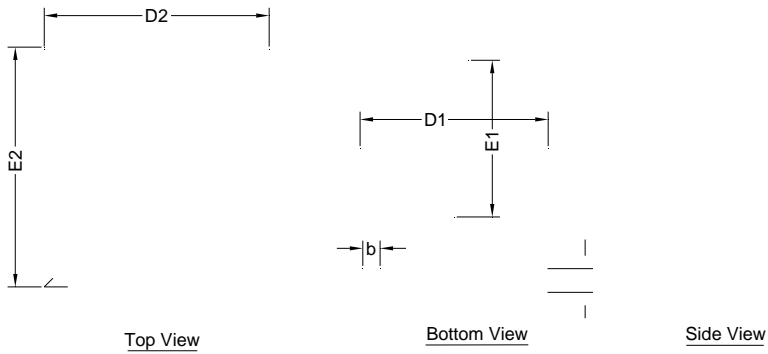


Figure D. Diode Recovery Test Circuit & Waveform



# YJG300G04AR

## PDFN5060-8L-D-0.95MM Package information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
D	5.15	5.35	5.55
E	5.95	6.05	6.15
A	0.85	0.95	1.00
A1	0.203 BSC		
A2			0.08
D1	4.25	4.35	4.45
E1	3.525	3.625	3.725
D2		5.20	
E2		5.55	
L1	0.45	0.55	0.65
L2	0.68 BSC		
b	0.3	0.4	0.5
e	1.27 BSC		

Note:

1. Controlling dimension: in millimeters.
2. General tolerance:  $\pm 0.10$ mm.
3. The pad layout is for reference purposes only.



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